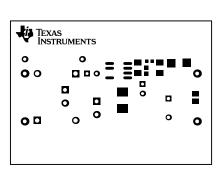
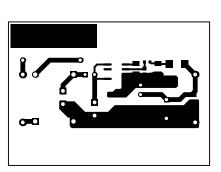


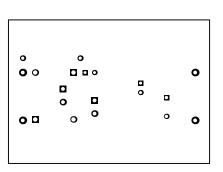
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9073	REV: A	SUN REU:	Not In VersionControl
LAYER NAME = Top Overlay				
PLOT NAME = Top Overlay	GENERATED : 8/5/20	9:04:15	AM	TEXAS INSTRUMENTS



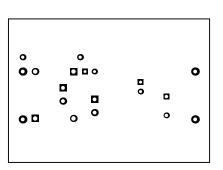
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9073	REV: A	SUN REU:	Not In VersionControl
LAYER NAME = Top Solder				
PLOT NAME = Top Solder Mask	GENERATED : 8/5/20	9:04:16	AM	TEXAS INSTRUMENTS



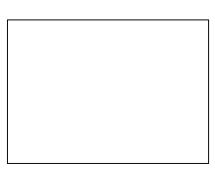
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9073	REV: A	SUN REV:	Not In VersionControl
LAYER NAME = Top Layer				
PLOT NAME = Top Layer	GENERATED : 8/5/20	9:04:16	AM	TEXAS INSTRUMENTS



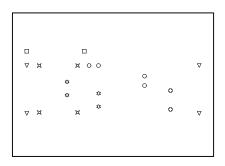
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9073	REV: A	SUN REU:	Not In VersionControl
LAYER NAME = Bottom Layer				
PLOT NAME = Bottom Layer	GENERATED : 8/5/20	9:04:16	AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9073	REV: A	SUN REV:	Not In VersionControl
LAYER NAME = Bottom Solder				
PLOT NAME = Bottom Solder Mask	GENERATED : 8/5/20	9:04:17	AM	TEXAS INSTRUMENTS



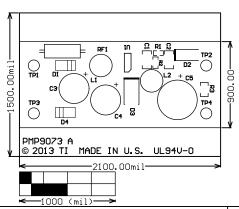
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9073	REU: A	SUN REU	: Not In VersionControl
LAYER NAME = Bottom Overlay				
PLOT NAME = Bottom Overlay	GENERATED : 8/5/20	013 9:04:17	AM	TEXAS INSTRUMENTS



Symbol	Hit Count	Tool Size	Plated	Hole Type
0	4	31mil (0.787mm)	PTH	Round
	2	33.465mil (0.85mm)	PTH	Round
0	2	35mil (0.889mm)	PTH	Round
*	4	39.37mil (1mm)	PTH	Round
$\nabla$	4	40mil (1.016mm)	PTH	Round
Ħ	4	45.276mil (1.15mm)	PTH	Round
	20 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9073	REV: A	SUN REU:	: Not In VersionControl
LAYER NAME = Drill Drawing				
PLOT NAME = Drill Drawing	GENERATED : 8/5/20	9:04:18	AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9073	REV: A	SUN REV:	: Not In VersionControl
LAYER NAME = M@pBOwedlDimensions				
PLOT NAME = Board Dimensions	GENERATED : 8/5/20	9:04:18	AM	TEXAS INSTRUMENTS

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